

IN THE CLAIMS:

Please cancel claims 4, 27, 28, and 34-67 without prejudice, amend claims 1, 3, and 29, and add new claims 68 and 69 so that pending claims 1, 3, 6-12, 14-26, 29-33, 68, and 69 read as follows:

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1. (Twice Amended) A method comprising:

depositing a plurality of singulated dice into a carrier, said carrier comprising a digital storage device;

testing said singulated dice while deposited in said carrier; and

storing in said digital storage device data indicating results of said testing of each of said dice.

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3. (Twice Amended) A method as in claim 1 further comprising storing an identification code in said digital storage device, wherein said identification code comprises information identifying at least one semiconductor wafer from which said dice were singulated.

6. (Previously Amended) A method as in claim 1 further comprising applying a die identification code to each of said singulated dice, each said die identification code comprising information relating to said die to which said die identification code is applied.

7. (Previously Amended) A method as in claim 6 wherein each said die identification code comprises information identifying the semiconductor wafer from which said die was singulated.

8. (Previously Amended) A method as in claim 7 wherein each said die identification code is applied to said die after said dice are deposited into and secured in said carrier.

9. (Previously Amended) A method as in claim 7 wherein each said die identification code further comprises information identifying a particular wafer processing lot in which the semiconductor wafer from which said die was singulated was created.

10. (Previously Amended) A method as in claim 8 wherein said die identification code is applied to said die through an opening in said carrier.
11. (Previously Amended) A method as in claim 1 wherein said testing comprises a burn-in testing.
12. (Previously Amended) A method as in claim 1 wherein said carrier secures said dice during use of said dice after said testing and said carrier acts as a final package for said dice.
14. (Previously Amended) A method as in claim 1 further comprising mounting a plurality of elongate, resilient electrical contact elements on contact pads of said dice.
15. (Previously Amended) A method as in claim 14 wherein said plurality of elongate, resilient electrical contact elements are mounted prior to depositing said dice into said carrier.
16. (Previously Amended) A method as in claim 1 further comprising applying a top on said carrier after depositing said dice into said carrier.
17. (Previously Amended) A method as in claim 14 further comprising mounting said carrier onto a substrate having a plurality of electrical contact pads.
18. (Previously Amended) A method as in claim 17 wherein said carrier is mounted on said substrate prior to depositing said dice onto said carrier.
19. (Previously Amended) A method as in claim 17 wherein said carrier is mounted on said substrate after depositing said dice onto said carrier.
20. (Previously Amended) A method as in claim 17 wherein each of said contact pads on said dice are electrically coupled to a corresponding one of said plurality of electrical contact pads on said substrate through a corresponding one of said elongate, resilient electrical contact elements.

21. A method as in claim 20 wherein each of said elongate, resilient electrical contact elements is freestanding.
22. A method as in claim 14 wherein each of said elongate, resilient electrical contact elements is freestanding.
23. (Previously Amended) A method as in claim 17 wherein said substrate is a test printed circuit board which is used in said testing.
24. (Previously Amended) A method as in claim 17 wherein said substrate is a final package unit for said dice.
25. (Previously Amended) A method as in claim 17 wherein said substrate is used in said testing, and if said dice pass said testing, said substrate is used to package said dice for use.
26. (Previously Amended) A method as in claim 25 wherein if said dice fail said testing, said dice are removed from said carrier and other dice are deposited into said carrier.
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- B³ 29. (Twice Amended) A method as in claim 1 further comprising:
mounting, prior to said testing, a plurality of elongate, resilient electrical contact elements on contact pads of said dice;
mounting, prior to said testing, said carrier onto a substrate having a plurality of electrical contact pads, wherein each of said contact pads on said dice are electrically coupled to a corresponding one of said plurality of electrical contact pads on said substrate through a corresponding one of said elongate, resilient electrical contact elements.
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30. A method as in claim 29 wherein each of said elongate, resilient electrical contact elements is freestanding.

31. (Previously Amended) A method as in claim 29 wherein each of said elongate, resilient electrical contact elements is compressed less during said testing than during final use of said dice.

32. (Previously Amended) A method as in claim 20 wherein each of said elongate, resilient electrical contact elements is compressed less during said testing than during final use of said dice.

33. (Previously Amended) A method as in claim 20 further comprising removing said dice from said carrier after said testing and packaging said dice for use.

68. (New) A method as in claim 1 further comprising, for each of said plurality of dice, storing in said digital storage device data identifying a location on the semiconductor wafer from which said die was singulated.

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69. (New) A method as in claim 68 further comprising constructing using data stored in said digital storage device a map of a semiconductor wafer from which at least two of said dice were singulated indicating a location on said wafer of each of said dice and an indication of whether each said die passed or failed said testing.
